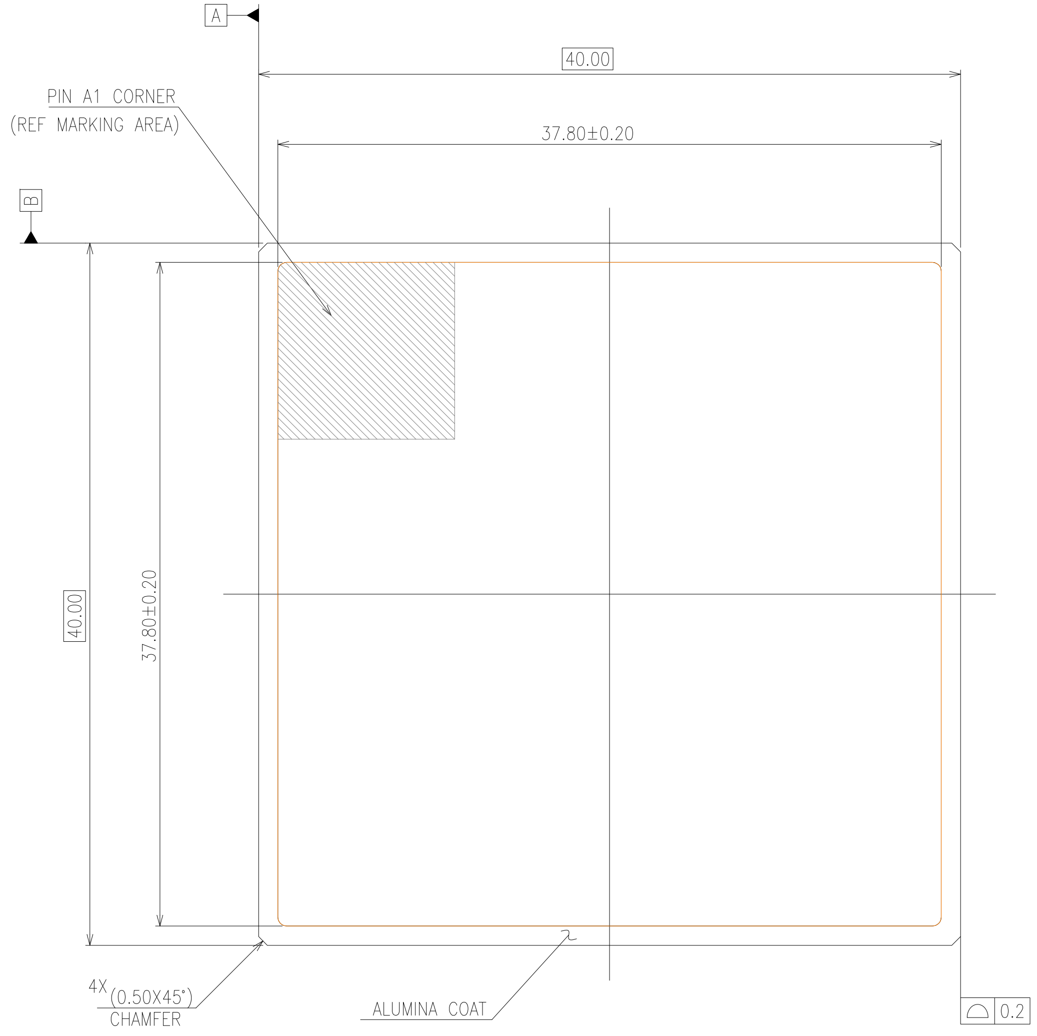
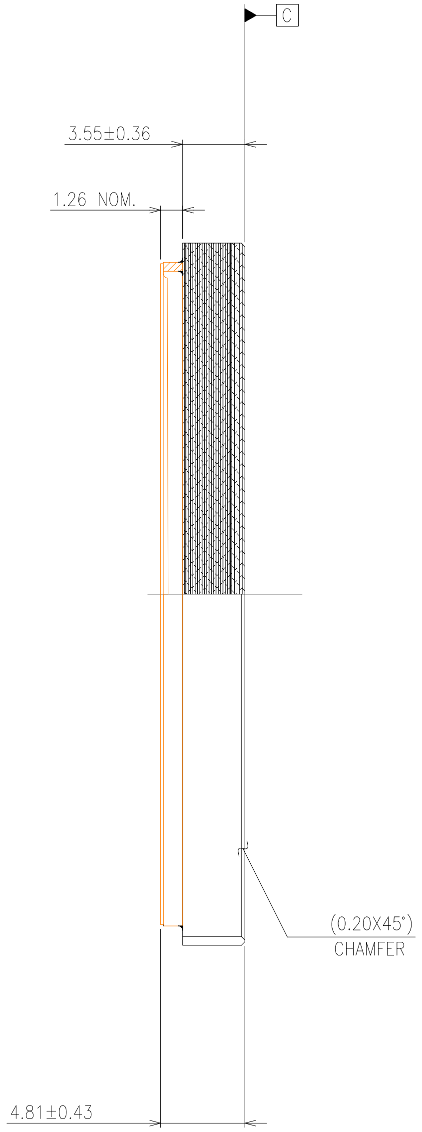
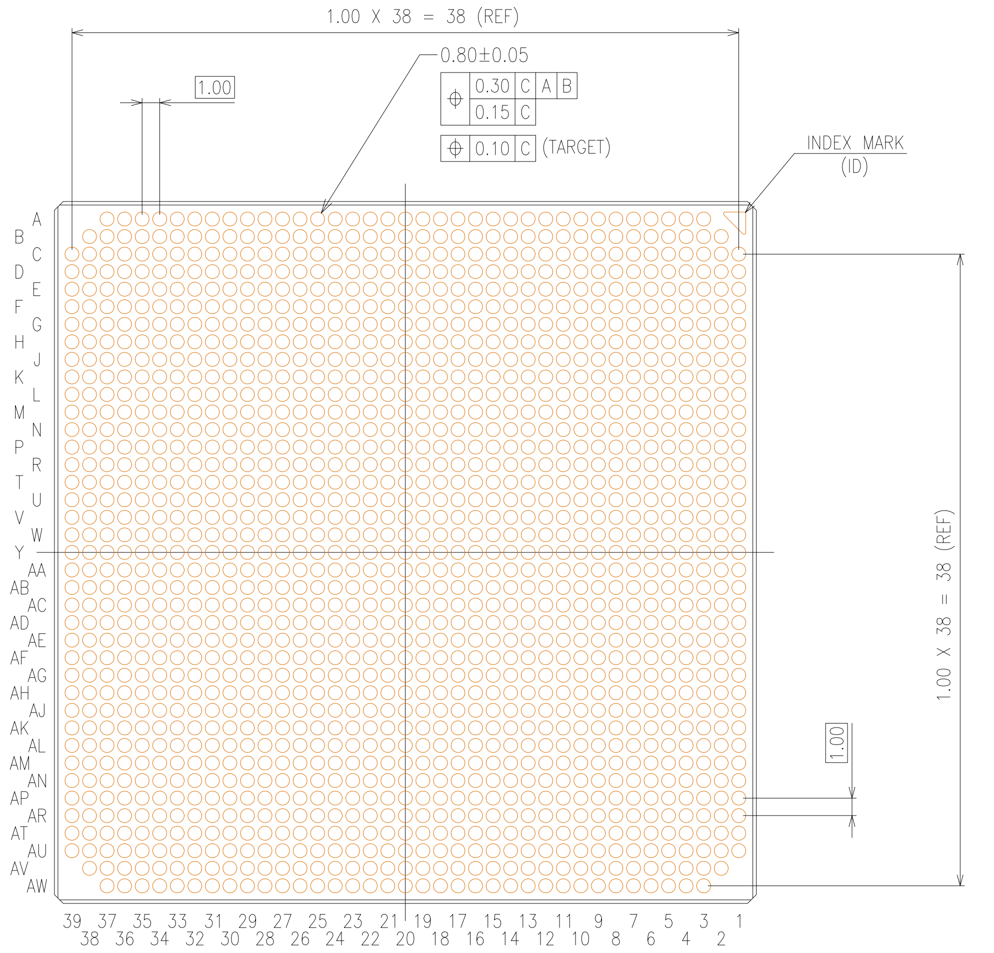
ECN NO.	REV.	DESCRIPTION OF CHANGE	ECN DATE	ORIGINATOR
20200047	0	First release.	02/03/2020	Erwin Q







GENERAL TOLERANCE
UNLESS OTHERWISE INDICATED

DECIMAL	ANGULAR
±0.20	±1°

DIMENSIONS: Millimeters (mm)

PROJECTION

APPROVALS	DATE
DRAWN: Erwin Quiobo	02/03/2020
CHECKED: Raymond Kuang	02/03/2020
ENG'R:	
RELEASED:	

MICROSEMI CORPORATION, FPGA BUSINESS UNIT
3850 N 1st St, San Jose, CA 995134

TITLE
LG1509, 40.0 MM X 40.0 MM, 1.0 MM PITCH, 1509 LAND PADS
FLIP CHIP, CERAMIC LAND GRID ARRAY, PACKAGE OUTLINE DRAWING

	MSCC DWG. NUMBER: 1-14-12042	REV 0
VENDOR NAME: KYOCERA	VENDOR DWG. NUMBER: KD-YB9353	REV –
LID DWG. NUMBER: ---	SCALE: NONE	SHEET 1 OF 1